A18 26

28

OEBA 27

LEBA [

31 B18 30 CLKBA

29 GND

SCBS242E – JUNE 1992 – REVISED FEBRUARY 1999

 Members of the Texas Instruments Widebus™ Family 	SN54ABT162500 WD PACKAGE SN74ABT162500 DL PACKAGE (TOP VIEW)
 B-Port Outputs Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required 	OEAB 1 56 GND LEAB 2 55 CLKAB
 State-of-the-Art EPIC-IIB[™] BiCMOS Design	A1 [] 3 54]] B1
Significantly Reduces Power Dissipation	GND [] 4 53]] GND
 UBT[™] (Universal Bus Transceiver)	A2 [] 5 52 [] B2
Combines D-Type Latches and D-Type	A3 [] 6 51 [] B3
Flip-Flops for Operation in Transparent,	V _{CC} [] 7 50 [] V _{CC}
Latched, or Clocked Mode	A4 [] 8 49 [] B4
• Typical V _{OLP} (Output Ground Bounce)	A5 [] 9 48]] B5
< 0.8 V at V _{CC} = 5 V, $T_A = 25^{\circ}C$	A6 [] 10 47]] B6
 High-Impedance State During Power Up	GND 11 46 GND
and Power Down	A7 12 45 B7
 Flow-Through Architecture Optimizes PCB Layout 	A8 1 13 44 B8 A9 1 14 43 B9 A10 15 42 B10
 Latch-Up Performance Exceeds 500 mA Per JESD 17 	A10 [13 42] B10 A11 [16 41] B11 A12 [17 40] B12
 ESD Protection Exceeds 2000 V Per	GND [18 39] GND
MIL-STD-883, Method 3015; Exceeds 200 V	A13 [19 38] B13
Using Machine Model (C = 200 pF, R = 0)	A14 [20 37] B14
 Package Options Include Plastic Shrink	A15 21 36 B15
Small-Outline (DL) Package and 380-mil	V _{CC} 22 35 V _{CC}
Fine-Pitch Ceramic Flat (WD) Package	A16 23 34 B16
Using 25-mil Center-to-Center Spacings	A17 [24 33] B17 GND [25 32] GND

description

These 18-bit universal bus transceivers combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, and clocked modes. Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs.

For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the high-to-low transition of CLKAB. Output-enable OEAB is active high. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B but uses OEBA, LEBA, and CLKBA. The output enables are complementary (OEAB is active high and OEBA is active low).

The B-port outputs, which are designed to source or sink up to 12 mA, include equivalent 25- Ω series resistors to reduce overshoot and undershoot.



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SCBS242E - JUNE 1992 - REVISED FEBRUARY 1999

description (continued)

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, OE should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

The SN54ABT162500 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT162500 is characterized for operation from -40°C to 85°C.

	OUTPUT										
OEAB	LEAB	CLKAB	Α	В							
L	Х	Х	Х	Z							
н	Н	Х	L	L							
н	Н	Х	Н	н							
н	L	\downarrow	L	L							
н	L	\downarrow	Н	н							
н	L	Н	Х	в ₀ ‡ в ₀ §							
Н	L	L	Х	в ₀ §							
+											

FUNCTION TABLE[†]

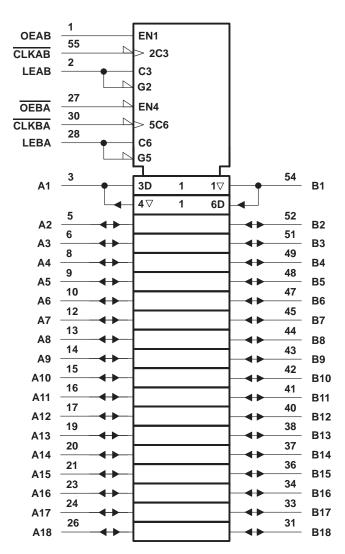
[†]A-to-B data flow is shown: B-to-A flow is similar but uses OEBA, LEBA, and CLKBA.

[‡]Output level before the indicated steady-state input conditions were established

§ Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low



logic symbol[†]

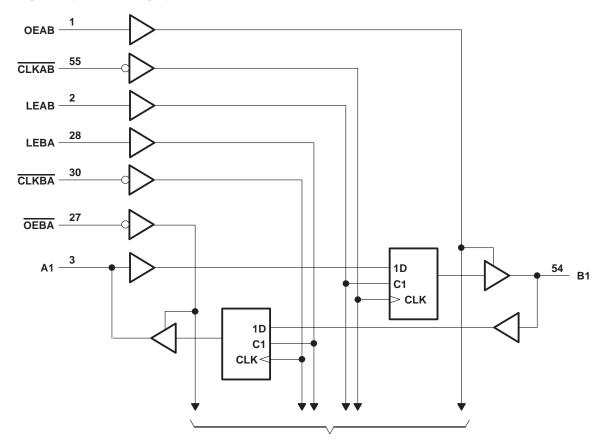


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



SCBS242E - JUNE 1992 - REVISED FEBRUARY 1999

logic diagram (positive logic)



To 17 Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, Vo	–0.5 V to 5.5 V
Current into any output in the low state, I _O : SN54ABT162500 (A port)	96 mA
SN74ABT162500 (A port)	128 mA
B port	30 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I_{OK} (V _O < 0)	
Package thermal impedance, θ_{JA} (see Note 2): DL package	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.



SCBS242E - JUNE 1992 - REVISED FEBRUARY 1999

recommended operating conditions (see Note 3)

			SN54ABT	162500	SN74ABT	UNIT	
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage		0.8		0.8	V	
VI	Input voltage	0	Vcc	0	VCC	V	
le	High lovel output current	A port	4	-24		-32	mA
ЮН	High-level output current	B port	4	-12		-12	mA
la.		A port	200	48		64	A
IOL	Low-level output current	B port	0	12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled	Q	10		10	ns/V
$\Delta t / \Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
Тд	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCBS242E - JUNE 1992 - REVISED FEBRUARY 1999

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST COL	т	A = 25°C	>	SN54ABT	162500	SN74ABT	UNIT				
PA	RAMETER	TEST COI	NDITIONS	MIN	ΜΙΝ ΤΥΡ [†] ΜΑΧ			MAX	MIN	MAX	UNIT		
VIK		V _{CC} = 4.5 V,	lı = -18 mA			-1.2		-1.2		-1.2	V		
		V _{CC} = 4.5 V,	I _{OH} = -3 mA	2.5			2.5		2.5				
	0	V _{CC} = 5 V,	I _{OH} = -3 mA	3			3		3				
	A port		I _{OH} = -24 mA	2			2						
Vari		V _{CC} = 4.5 V	I _{OH} = -32 mA	2*					2		V		
Vон		V _{CC} = 4.5 V,	I _{OH} = -1 mA	3.35			3.3		3.35		v		
	P. nort	$V_{CC} = 5 V,$	I _{OH} = -1 mA	3.85			3.8		3.85				
	B port	V _{CC} = 4.5 V	I _{OH} = -3 mA	3.1			3		3.1				
		VCC = 4.5 V	I _{OH} = -12 mA	2.6					2.6				
	A port		I _{OL} = 48 mA			0.55		0.55					
VOL	A port	V _{CC} = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V		
	B port	V _{CC} = 4.5 V,	I _{OL} = 12 mA			0.8		0.8		0.8			
V _{hys}					100						mV		
II Control inputs A or B ports		$V_{CC} = 0$ to 5.5 V, V			±1		±1		±1				
		$V_{CC} = 2.1 V \text{ to } 5.5$ $V_{I} = V_{CC} \text{ or GND}$	±2		±20		±20		±20				
IOZPU	J	$V_{CC} = 0 \text{ to } 2.1 \text{ V},$ $V_{O} = 0.5 \text{ V to } 2.7 \text{ V}$	$\sqrt{0E}$ or $OE = X$			±50	UCY UCY	±50		±50 μA			
IOZPE)	$V_{CC} = 2.1 V \text{ to } 0,$ $V_{O} = 0.5 V \text{ to } 2.7 V$	$\sqrt{10E} \text{ or } OE = X$			±50	PROL	±50		±50	μΑ		
IOZH‡	ŧ	$V_{CC} = 2.1 \text{ V} \text{ to } 5.5$ $V_{O} = 2.7 \text{ V}, \text{ OE} \ge 2$	V, V or OE \leq 0.8 V			10		10		10	μA		
I _{OZL} ‡	:	$V_{CC} = 2.1 \text{ V to } 5.5$ $V_{O} = 0.5 \text{ V}, \text{ OE} \ge 2$	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V},$ $V_{O} = 0.5 \text{ V}, \text{ OE} \ge 2 \text{ V or OE} \le 0.8 \text{ V}$			-10		-10		-10	μΑ		
loff		V _{CC} = 0,	$V_{I} \text{ or } V_{O} \leq 4.5 \text{ V}$			±100				±100	μA		
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ		
	A port			-50	-110	-180	-50	-180	-50	-180			
10¶	B port	VCC = 5.5 V,	V _O = 2.5 V	-25	-55	-90	-25	-90	-25	-90	mA		
		V _{CC} = 5.5 V,	Outputs high			3		3		3			
ICC	A or B ports	$V_{CC} = 3.3 V,$ $I_{O} = 0,$	Outputs low			36		36		36	mA		
		$V_{I} = V_{CC}$ or GND	Outputs disabled			3		3		3			
∆ICC [#]	ŧ	$V_{CC} = 5.5 V$, One i Other inputs at V_{CC}				50		50		50	μΑ		
Ci	Control inputs	V _I = 2.5 V or 0.5 V			3						pF		
C _{io}	A or B ports	V _O = 2.5 V or 0.5 \	/		9						pF		

* On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5$ V.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ For V_{CC} between 2.1 V and 4 V, OE should be less than or equal to 0.5 V to ensure a low state.

Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[#]This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



SCBS242E - JUNE 1992 - REVISED FEBRUARY 1999

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

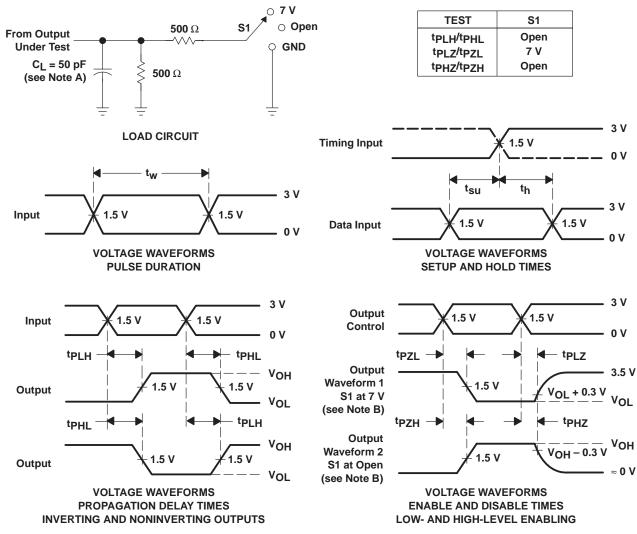
				SN54ABT	162500	SN74ABT	162500	UNIT	
				MIN	MAX	MIN	MAX	UNIT	
fclock	Clock frequency				150		150	MHz	
t _w Pulse duration	LEAB or LEBA high		2.5	h	2.5		ns		
	Puise duration	CLKAB or CLKBA high or low	3	VIE	3		115		
		A before CLKAB↓	3.3	RE	3.3				
	Cotur time	B before CLKBA↓		3.3	ζ	3.3		~~	
t _{su}	Setup time			40		1		ns	
		A before LEAB to before LEBA	A before LEAB↓ or B before LEBA↓ CLK low			2.5			
4 .	Hold time	A after $\overline{CLKAB}\downarrow$ or B after $\overline{CLKBA}\downarrow$		Q 0		0			
th		A after LEAB \downarrow or B after LEBA \downarrow	A after LEAB \downarrow or B after LEBA \downarrow					ns	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT	162500	SN74ABT	UNIT	
		(001101)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			150	200		150		150		MHz
^t PLH	A or B	B or A	1.5	2.6	4	1.5	5.1	1.5	4.8	ns
^t PHL	AUB		2	3.4	5.2	2	6.1	2	5.7	115
^t PLH	LEAB or LEBA	B or A	2	3.3	4.8	2	6.1	2	5.6	ns
^t PHL	LEAD OF LEDA	BUIA	2	3.8	5.2	2 0	6.4	2	5.9	115
^t PLH		B or A	1.5	3.7	4.9	1.5	6.4	1.5	5.9	ns
^t PHL	CLKAB or CLKBA	BUIA	1.5	3.8	5.2	1.5	6.4	1.5	6	115
^t PZH		B or A	1.5	3.4	4.6	x 1.5	5.6	1.5	5.3	ns
^t PZL	OEAB or OEBA	BUIA	2	3.8	4.7	2	5.6	2	5.4	115
^t PHZ		R or A	2	4.5	5.7	2	6.9	2	6.5	ns
^t PLZ	OEAB or OEBA	B or A	1.5	3.8	5.3	1.5	6.3	1.5	5.8	115



SCBS242E - JUNE 1992 - REVISED FEBRUARY 1999



PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	e Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ABT162500DL	ACTIVE	SSOP	DL	56	20	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162500	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <= 1000ppm threshold. Antimony trioxide based flame retardants must also meet the <= 1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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5-Jan-2022

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
SN74ABT162500DL	DL	SSOP	56	20	473.7	14.24	5110	7.87

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